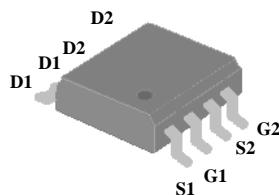




▼ Low On-resistance

▼ Single Drive Requirement

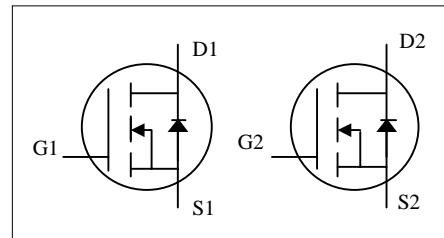
▼ Surface Mount Package



| | |
|--------------|---------------|
| BV_{DSS} | 60V |
| $R_{DS(ON)}$ | 100m Ω |
| I_D | 3.3A |

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.

**Absolute Maximum Ratings**

| Symbol | Parameter | Rating | Units |
|--------------------------|---------------------------------------|------------|---------------|
| V_{DS} | Drain-Source Voltage | 60 | V |
| V_{GS} | Gate-Source Voltage | ± 25 | V |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current ³ | 3.3 | A |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current ³ | 2.7 | A |
| I_{DM} | Pulsed Drain Current ¹ | 20 | A |
| $P_D @ T_A = 25^\circ C$ | Total Power Dissipation | 2 | W |
| | Linear Derating Factor | 0.016 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Value | Unit |
|-------------|---|-------|--------------|
| R_{thj-a} | Maximum Thermal Resistance, Junction-ambient ³ | 62.5 | $^\circ C/W$ |



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--|---|---|------|------|-----------|---------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 60 | - | - | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_j$ | Breakdown Voltage Temperature Coefficient | Reference to 25°C , $I_{\text{D}}=1\text{mA}$ | - | 0.04 | - | $\text{V}/^\circ\text{C}$ |
| $R_{\text{DS}(\text{ON})}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=3\text{A}$ | - | - | 100 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=2\text{A}$ | - | - | 125 | $\text{m}\Omega$ |
| $V_{\text{GS}(\text{th})}$ | Gate Threshold Voltage | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 1 | - | 3 | V |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=10\text{V}, I_{\text{D}}=3\text{A}$ | - | 6 | - | S |
| I_{DSS} | Drain-Source Leakage Current ($T_j=25^\circ\text{C}$) | $V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 10 | μA |
| | Drain-Source Leakage Current ($T_j=70^\circ\text{C}$) | $V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 25 | μA |
| I_{GSS} | Gate-Source Leakage | $V_{\text{GS}}=\pm 25\text{V}$ | - | - | ± 100 | nA |
| Q_g | Total Gate Charge ² | $I_{\text{D}}=3\text{A}$ | - | 6 | 10 | nC |
| Q_{gs} | Gate-Source Charge | $V_{\text{DS}}=48\text{V}$ | - | 2 | - | nC |
| Q_{gd} | Gate-Drain ("Miller") Charge | $V_{\text{GS}}=4.5\text{V}$ | - | 3 | - | nC |
| $t_{\text{d}(\text{on})}$ | Turn-on Delay Time ² | $V_{\text{DS}}=30\text{V}$ | - | 6 | 12 | ns |
| t_r | Rise Time | $I_{\text{D}}=1\text{A}$ | - | 5 | 12 | ns |
| $t_{\text{d}(\text{off})}$ | Turn-off Delay Time | $R_G=3.3\Omega, V_{\text{GS}}=10\text{V}$ | - | 16 | 32 | ns |
| t_f | Fall Time | $R_D=30\Omega$ | - | 3 | 8 | ns |
| C_{iss} | Input Capacitance | $V_{\text{GS}}=0\text{V}$ | - | 510 | 810 | pF |
| C_{oss} | Output Capacitance | $V_{\text{DS}}=25\text{V}$ | - | 55 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | f=1.0MHz | - | 35 | - | pF |
| R_g | Gate Resistance | f=1.0MHz | - | 1.3 | - | Ω |

Source-Drain Diode

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|-----------------|------------------------------------|---|------|------|------|-------|
| V_{SD} | Forward On Voltage ² | $I_{\text{S}}=1.7\text{A}, V_{\text{GS}}=0\text{V}$ | - | - | 1.2 | V |
| t_{rr} | Reverse Recovery Time ² | $I_{\text{S}}=4\text{A}, V_{\text{GS}}=0\text{V},$ | - | 27 | 54 | ns |
| Q_{rr} | Reverse Recovery Charge | $dI/dt=100\text{A}/\mu\text{s}$ | - | 32 | - | nC |

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t \leq 10sec ; 135 °C/W when mounted on Min. copper pad.

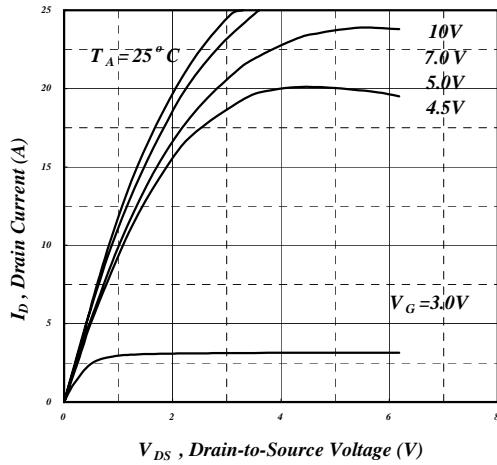


Fig 1. Typical Output Characteristics

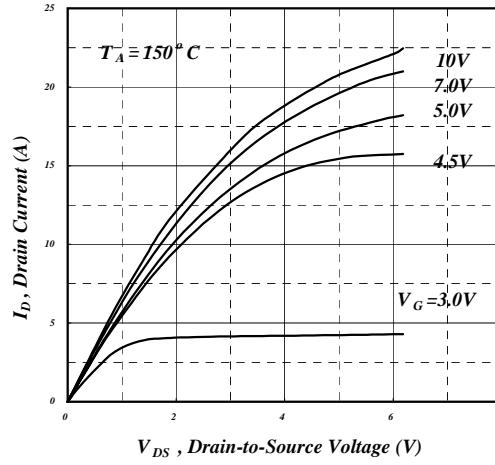


Fig 2. Typical Output Characteristics

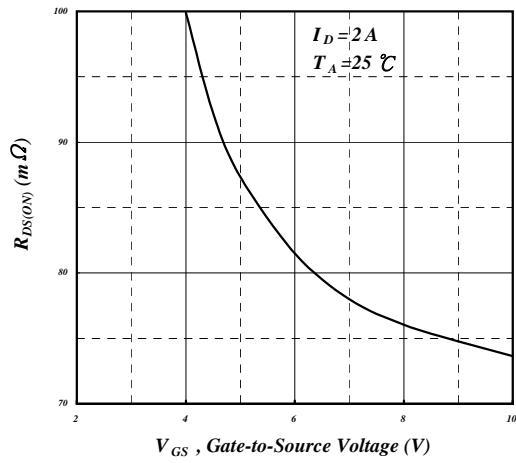


Fig 3. On-Resistance v.s. Gate Voltage

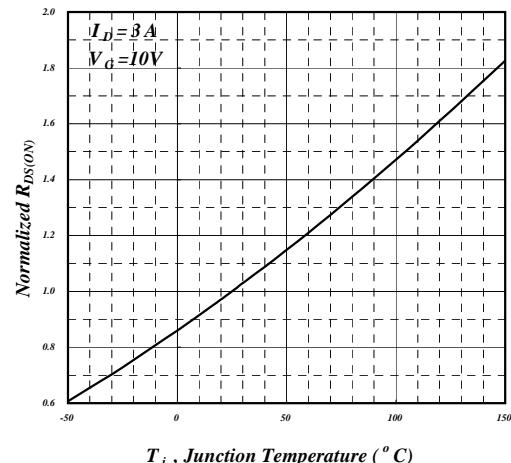


Fig 4. Normalized On-Resistance v.s. Junction Temperature

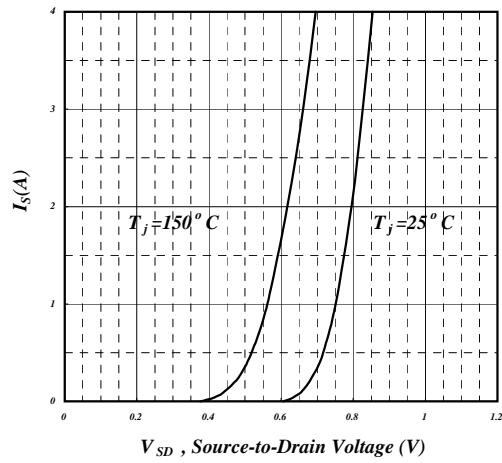


Fig 5. Forward Characteristic of Reverse Diode

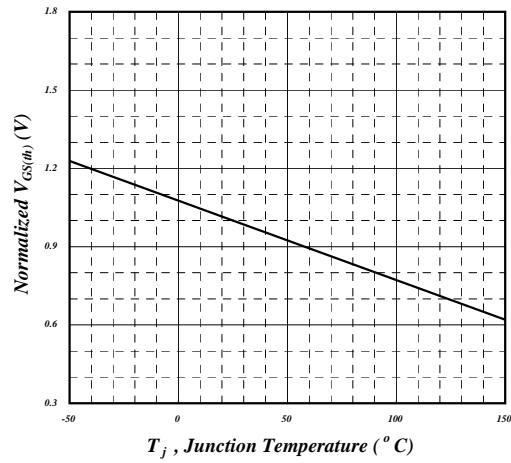
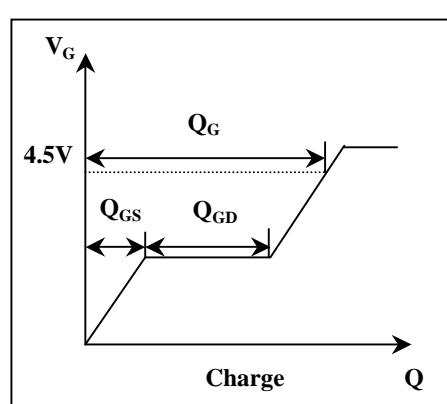
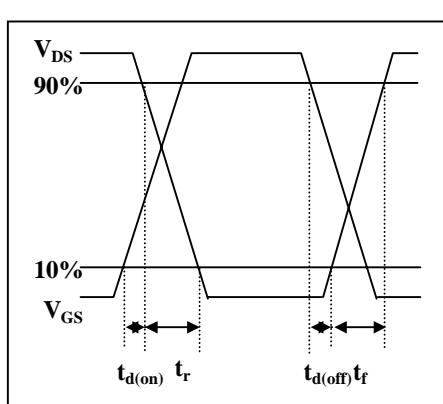
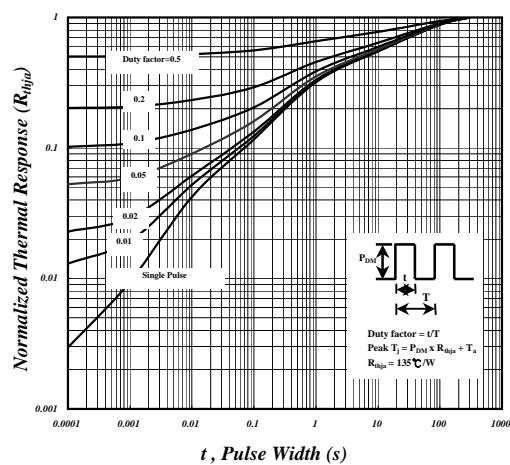
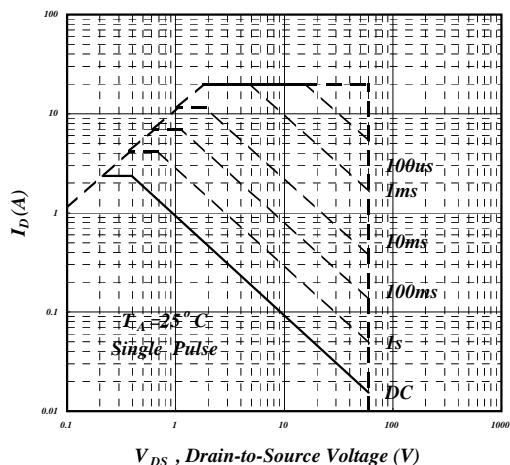
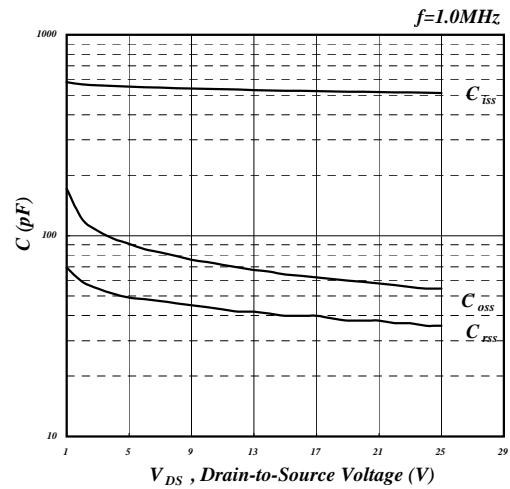
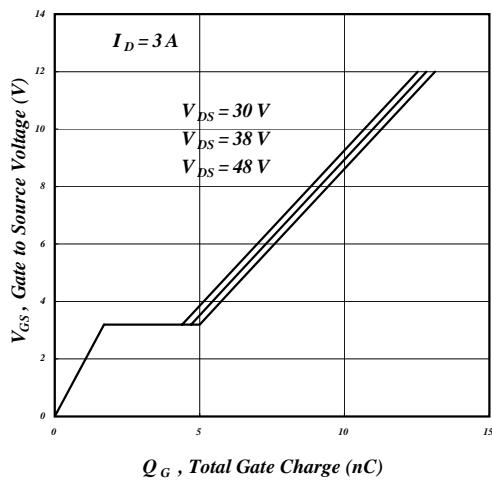


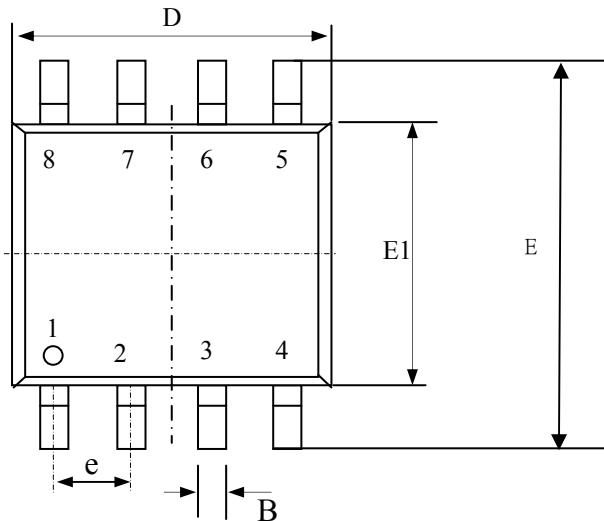
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



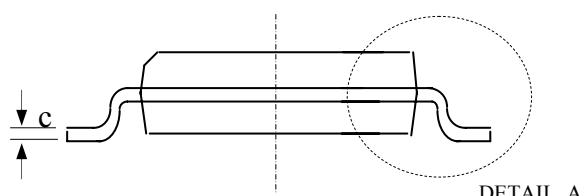
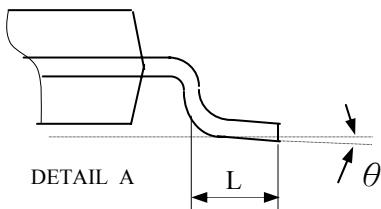
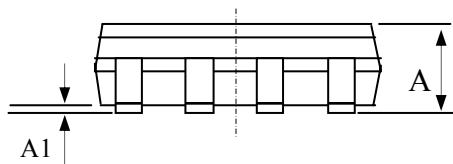


ADVANCED POWER ELECTRONICS CORP.

Package Outline : SO-8



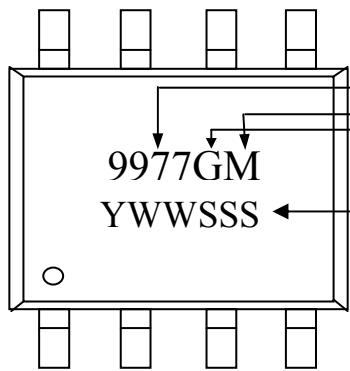
| SYMBOLS | Millimeters | | |
|----------|-------------|------|------|
| | MIN | NOM | MAX |
| A | 1.35 | 1.55 | 1.75 |
| A1 | 0.10 | 0.18 | 0.25 |
| B | 0.33 | 0.41 | 0.51 |
| C | 0.19 | 0.22 | 0.25 |
| D | 4.80 | 4.90 | 5.00 |
| E1 | 3.80 | 3.90 | 4.00 |
| E | 5.80 | 6.15 | 6.50 |
| L | 0.38 | 0.71 | 1.27 |
| θ | 0 | 4.00 | 8.00 |
| e | 1.27 TYP | | |



1. All Dimension Are In Millimeters.

2. Dimension Does Not Include Mold Protrusions.

Part Marking Information & Packing : SO-8



Part Number

Package Code

meet RoHS requirement

9977GM

YWWSSSS

Date Code (YWWSSSS)

Y : Last Digit Of The Year

WW : Week

SSS : Sequence